



US 20090134483A1

(19) **United States**(12) **Patent Application Publication****Weng et al.**(10) **Pub. No.: US 2009/0134483 A1**(43) **Pub. Date: May 28, 2009**(54) **ELECTRONIC ASSEMBLY FOR IMAGE SENSOR DEVICE**(52) **U.S. Cl. .... 257/432; 257/E31.127**(76) Inventors: **Jui-Ping Weng**, Miaoli (TW);  
**Tzu-Han Lin**, Hsinchu (TW)(57) **ABSTRACT**

Correspondence Address:

**Joe McKinney Muncy****PO Box 1364****Fairfax, VA 22038-1364 (US)**

An electronic assembly for an image sensor device is disclosed. The electronic assembly comprises a package module and a lens set mounted thereon. The package module comprises a device substrate comprising at least one grounding plug therein, in which the grounding plug is insulated from the device substrate and an array of optoelectronic devices therein. A transparent substrate comprises a dam portion attached to the device substrate to form a cavity between the device and transparent substrates. A micro-lens array is disposed within the cavity. A conductive layer is electrically connected to the grounding plug and covers the sidewalls of the lens set and the package module and the upper surface of the lens set. A method for fabricating the electronic assembly is also disclosed.

(21) Appl. No.: **11/944,558**(22) Filed: **Nov. 23, 2007****Publication Classification**(51) **Int. Cl.**  
**H01L 31/0232** (2006.01)